Final Product/Process Change Notification

Document #:FPCN23660XH
Issue Date:09 Jan 2024

Title of Change:	Wafer Fab Site Addition of onsemi, Aizu Japan as an Alternate Fab Site for ONC25BCD.
Proposed First Ship date:	16 Apr 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Jonathan.Bass@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	No change to marking / Changed material may be identified by date code
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Aizu, Japan	None

Description and Purpose:

onsemi would like to inform its customers that we will be qualifying an additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu, Japan for the devices listed in this FPCN.

The wafer technology was previously qualified in 2021 and multiple products are already running production on this flow. These changes can be found under FPCN23660 series.

Upon completion of the qualification, all products listed here will be dual sourced from its current wafer fab facility in onsemi wafer fab in Gresham, US or onsemi, Aizu, Japan

	From	**To**
Fab Site	onsemi Gresham, US	onsemi Gresham, US or onsemi Aizu, Japan

There will be no change to the orderable part number.

There will be no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME: NCP4318ALKDR2G
RMS: O90520
PACKAGE: SOIC-8

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=105°C, 100 % max rated Vcc	1008 hrs	0/80
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/80
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	0/240
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/80
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/80
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Part Number	Qualification Vehicle
NCP4318AHDDR2G	NCP4318ALKDR2G
NCP4318ALKDR2G	NCP4318ALKDR2G
NCP4318BLCDR2G	NCP4318ALKDR2G
NCP4318ALSDR2G	NCP4318ALKDR2G
NCP4318ALLDR2G	NCP4318ALKDR2G
NCP4318ALCDR2G	NCP4318ALKDR2G
NCP4318AHJDR2G	NCP4318ALKDR2G